

In the Specification:

Please add a new section directly before the "Technical Field" on page 1 as follows:

CROSS REFERENCE TO RELATED APPLICATION

This application is a divisional application of United States Patent Application No. 09/641,498 entitled "METHODS FOR FINISHING MICROELECTRONIC DEVICE PACKAGES," filed on August 18, 2000, now Patent No. _____, which is hereby incorporated by reference in its entirety.

Please amend the first full paragraph on page 5 (lines 7-18) as follows:

Figure 1 is an isometric view of a plurality of packaged microelectronic devices 100 before being processed in accordance with an embodiment of the invention. The microelectronic devices 100 can each have a microelectronic die 102, a printed circuit substrate 103 or lead frame to which each die 102 is attached, and a protective casing 110 covering each die 102. The dies 102 can be memory devices or processors that include integrated circuitry in a semiconductor substrate, or the dies 102 can be other types of microelectronic components. The printed circuit substrates 103 can each have a plurality of ball-pads 104 and traces 105 extending from the ball-pads 104. The traces 105 are coupled to corresponding bond-pads (not shown) on the die 102. The printed circuit substrates 103 shown in Figure 1 are initially part of an interposing substrate assembly 106, which may remain intact during the abrasion processes discussed below (as is evident in Figures 3-5). During Back-End-of-Line (BEOL) processing, the interposing substrate assembly 106 is cut to separate individual packaged devices 100 from one another.

Please delete the current Abstract (on the last page) and replace it with the following:

This disclosure provides methods for finishing or refurbishing surfaces on protective covers encapsulating microelectronic devices. One implementation permits simultaneous finishing of a surface of a protective package on each of a plurality of microelectronic devices carried on a common substrate. For example, at least a portion of the surface of each package may be etched to remove a layer of material from the package. Residual materials and/or chemicals can be cleaned from the package after terminating the etching of the package surface. After the etching is terminated, the common substrate may be cut to separate the microelectronic devices from one another. Other implementations of the invention employ different approaches, e.g., ablation or embossing, to control surface qualities of microelectronic device packages.